



LG-03IR4C94C-302BA-B1 **DATA SHEET**

SPEC. NO. : <u>SZ20071701</u>
DATE : <u>2020/07/17</u>
DEV <u>A/0</u>

REV. A/0

Approved By: Checked By: Prepared By:

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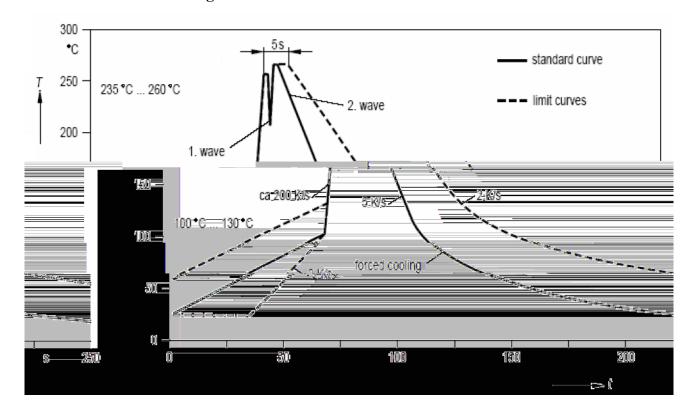
Electrical Optical Characteristics at Ta=25°C

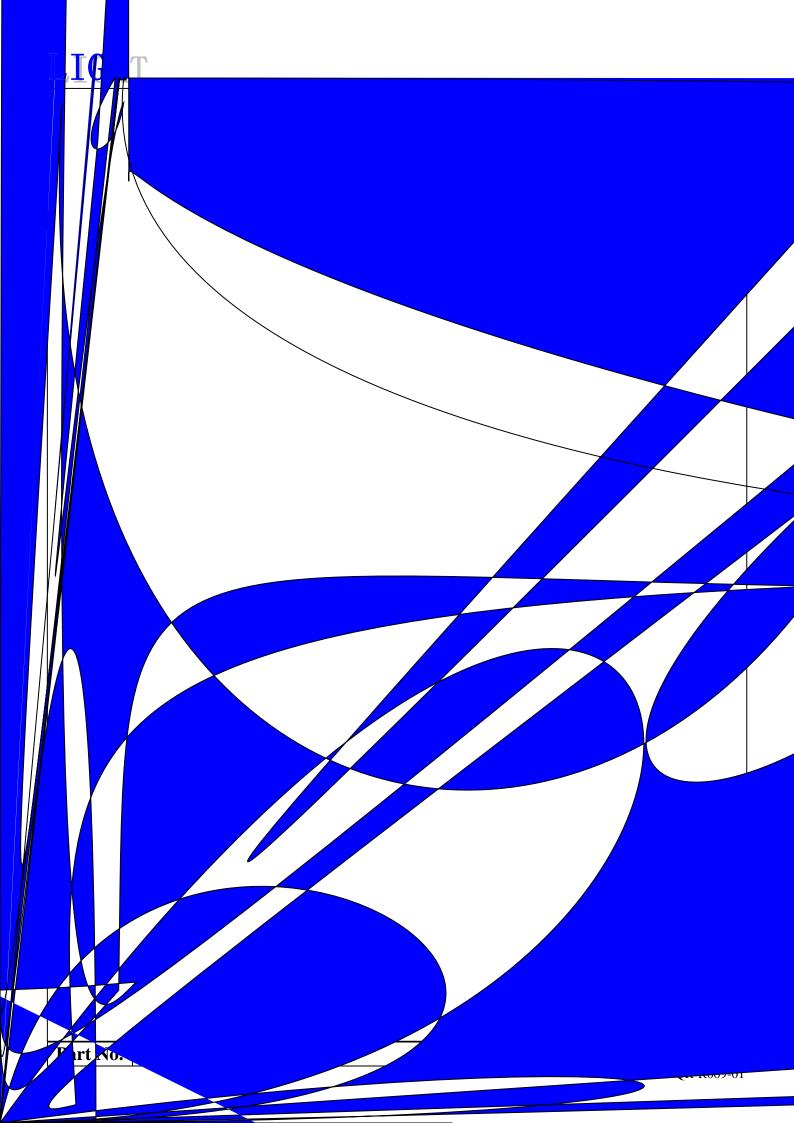
Parameter	Symbol	Min.	Тур.	Max.	Unit	Test Condition
Radiant Intensity	Ie	25	30		mW/sr	I _F =50mA (Note 1,3)
Viewing Angle	1/2		30		deg	(Note 2)
Peak Wavelength			940		nm	I _F =20mA
Spectral Line Half- Width			50		nm	I _F =20mA
Forward Voltage	V_{F}		1.25	1.5	V	I _F =50mA
Reverse Current	I_R			100	μА	V _R =5V

Note:

- 1. Point sources of the amount of radiation per unit time in a given direction within the unit solid Angle radiated energy.
- 2. 1/2 is the off-axis angle at which the Radiant Intensity is half the axial Radiant Intensity.
- 3. The Ie guarantee should be added $\pm 15\%$ tolerance.

Recommended Wave Soldering Profile









LED MOUNTING METHOD

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures (Fig.1).

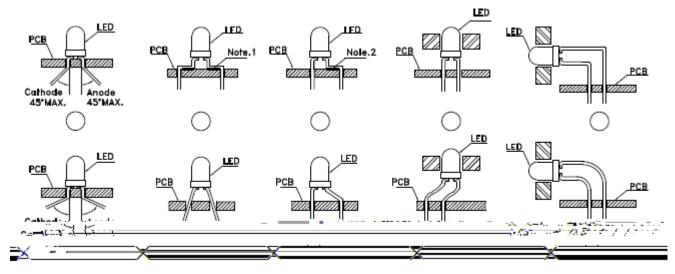
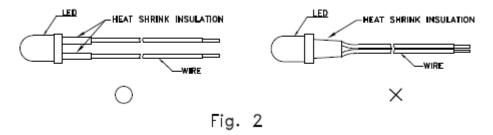


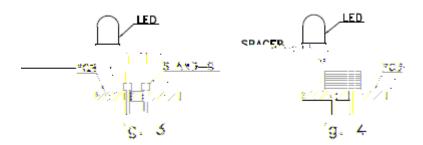
Fig. 1

Note 1-2: Do not route PCB trace in the contact area between the lead frame and the PCB to prevent short-circuits.

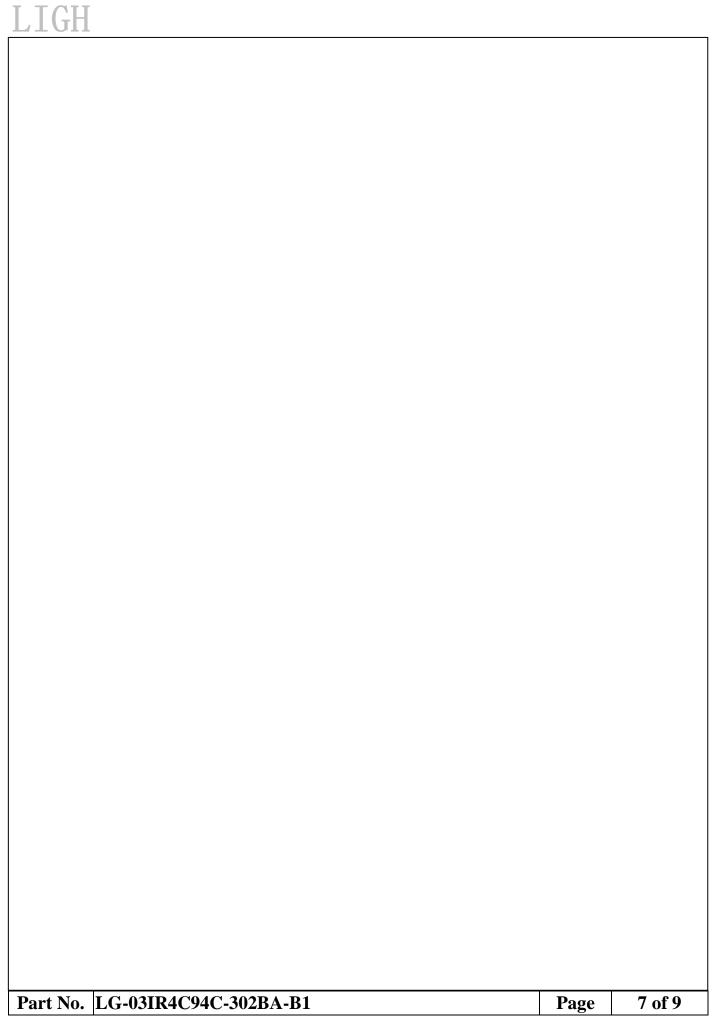
2. When soldering wire to the LED, use individual heat-shrink tubing to insulate the exposed leads to prevent accidental contact short-circuit (Fig.2).



3. Use stand-offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.



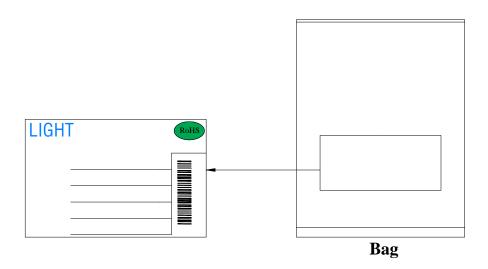
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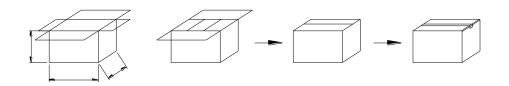


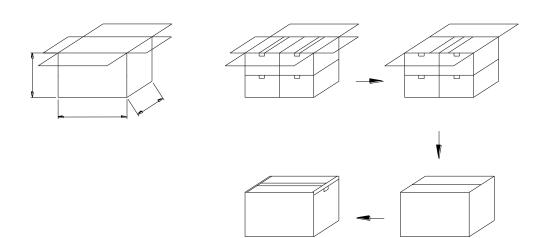
LIGHT



PACKAGE







Bag minimum volume	Bag volume	Inner box volume	Outer carton volume
(pcs / Bag)	(pcs / Bag)	(Bag / box)	(Box / Carton)
250	1000	10	4

